

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Title: METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE

Docket No.: 303.601US3  
Filed: November 26, 2003  
Examiner: James Mitchell  
Confirmation No.: 8165

Serial No.: 10/722,838  
Due Date: September 27, 2008 (Saturday)  
Group Art Unit: 2813

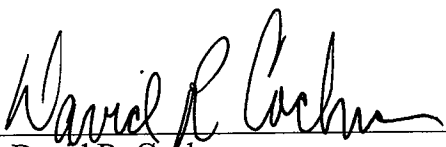
Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

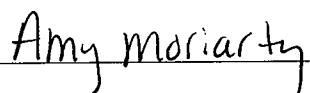
- ☒ Amendment and Response under 1.111 (16 pgs.)
- ☒ Supplemental Information Disclosure Statement (3 pgs.), Form 1449 (1 pg.) Copies of Cited References (2).
- ☒ Authorization to charge Deposit Account 19-0743 in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).
- ☒ Formal Drawings (12 pgs.)

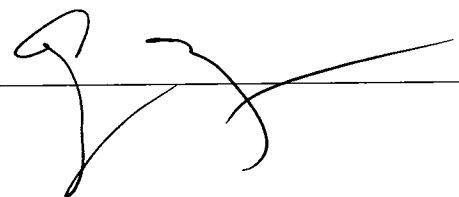
Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.  
Customer No.: 21186

By:   
David R. Cochran  
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Mail Stop Amendment Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 29th day of September, 2008.

  
Name

  
Signature